



HM94

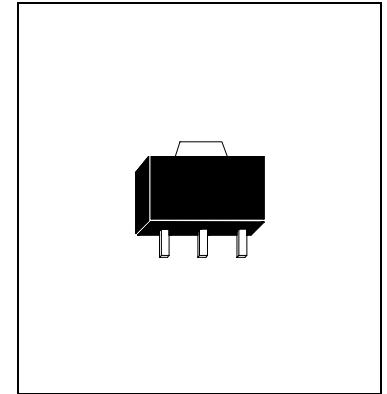
PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HM94 is designed for application requires high voltage.

Features

- High voltage: $V_{CEO}=400V(\text{min})$ at $I_C=1\text{mA}$
- High current gain: $I_C=300\text{mA}$ at 25°C
- Complementary with HM44



Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature $-55 \sim +150^\circ\text{C}$
Junction Temperature $+150^\circ\text{C}$ Maximum
- Maximum Power Dissipation
Total Power Dissipation ($T_a=25^\circ\text{C}$) 1 W
- Maximum Voltages and Currents ($T_a=25^\circ\text{C}$)
VCBO Collector to Base Voltage -400 V
VCEO Collector to Emitter Voltage -400 V
VEBO Emitter to Base Voltage -6 V
IC Collector Current -500 mA

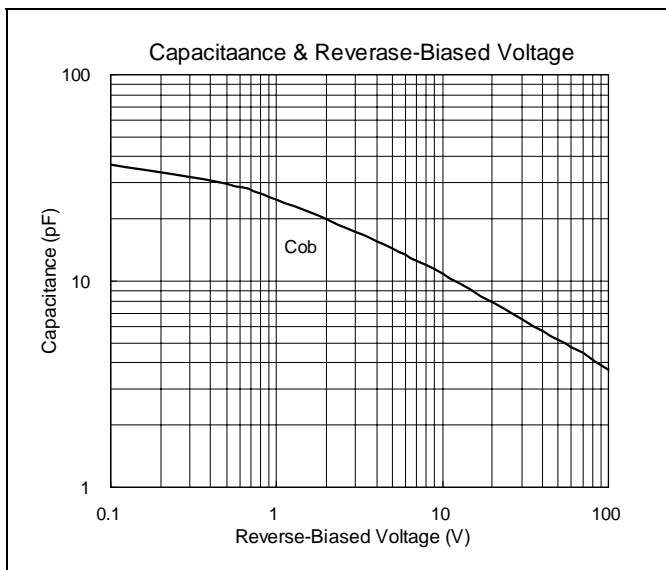
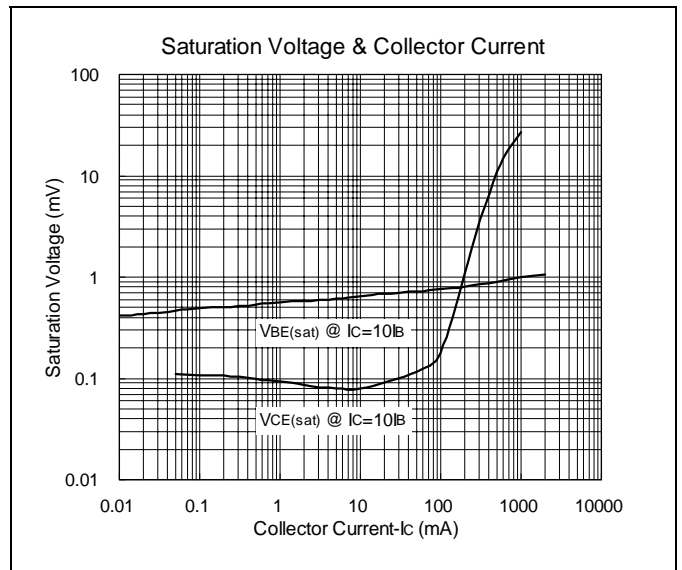
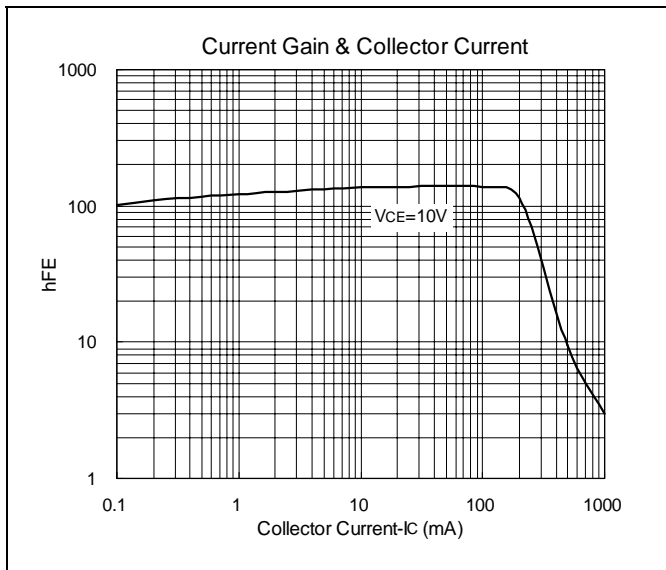
Characteristics ($T_a=25^\circ\text{C}$)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-400	-	-	V	$I_C=-100\mu\text{A}$
BVCEO	-400	-	-	V	$I_C=-1\text{mA}$
BVEBO	6	-	-	V	$I_E=-10\mu\text{A}$
ICBO	-	-	-100	nA	$V_{CB}=-400\text{V}$
IEBO	-	-	-100	nA	$V_{EB}=-6\text{V}$
ICES	-	-	-500	nA	$V_{CE}=-400\text{V}, V_{BE}=0$
*VCE(sat)1	-	-	-350	mV	$I_C=-1\text{mA}, I_B=-0.1\text{mA}$
*VCE(sat)2	-	-	-500	mV	$I_C=-10\text{mA}, I_B=-1\text{mA}$
*VCE(sat)3	-	-	-750	mV	$I_C=-50\text{mA}, I_B=-5\text{mA}$
*VBE(sat)	-	-	-750	mV	$I_C=-10\text{mA}, I_B=-1\text{mA}$
*hFE1	40	-	-		$V_{CE}=-10\text{V}, I_C=-1\text{mA}$
*hFE2	50	-	300		$V_{CE}=-10\text{V}, I_C=-10\text{mA}$
*hFE3	45	-	-		$V_{CE}=-10\text{V}, I_C=-50\text{mA}$
*hFE4	40	-	-		$V_{CE}=-10\text{V}, I_C=-100\text{mA}$

*Pulse Test : Pulse Width $\leq 380\mu\text{s}$, Duty Cycle $\leq 2\%$



Characteristics Curve





SOT-89 Dimension

Marking :

Style : Pin 1.Base 2.Collector 3.Emitter

3-Lead SOT-89 Plastic Surface Mounted Package
 HSMC Package Code : M

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.52
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.0141	0.0201	0.36	0.51					

Notes : 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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